SN5410, SN54LS10, SN54S10, SN7410, SN74LS10, SN74S10 TRIPLE 3-INPUT POSITIVE-NAND GATES SDLS035A – DECEMBER 1983 – REVISED APRIL 2003

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

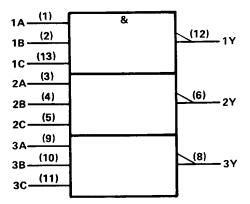
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7410, SN74LS10, and SN74S10 are characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE	leach	gate)
----------------	-------	-------

11	VPUT	S	OUTPUT
A	В	с	Y
н	н	н	L
L	X	x	н
x	L	x	н
x	х	εl	н

logic symbol[†]



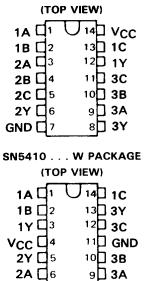
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

positive logic

$$Y = \overline{A \cdot B \cdot C}$$
 or $Y = \overline{A} + \overline{B} + \overline{C}$

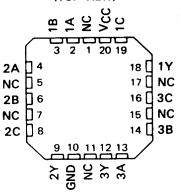
SN5410 . . . J PACKAGE SN54LS10, SN54S10 . . . J OR W PACKAGE SN7410 . . . N PACKAGE SN74LS10, SN74S10 . . . D OR N PACKAGE



SN54LS10, SN54S10 . . . FK PACKAGE (TOP VIEW)

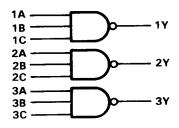
8 **2**C

2B 🗌



NC - No internal connection

logic diagram (positive logic)



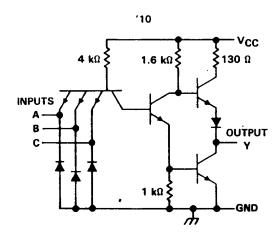
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

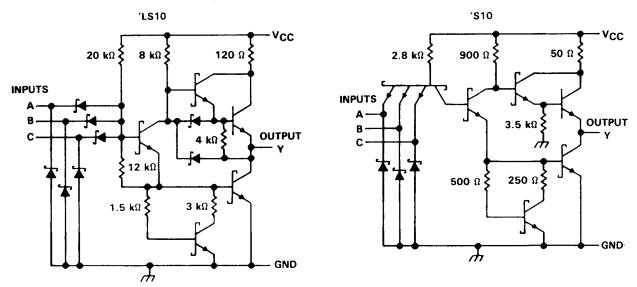


SN5410, SN54LS10, SN54S10, SN7410, SN74LS10, SN74S10 TRIPLE 3-INPUT POSITIVE-NAND GATES SDLS035A - DECEMBER 1983 - REVISED APRIL 2003

SDLS035A – DECEMBER 1983 – REVISED API

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7V
Input voltage: '10, 'S10	
'LS10	7 V
Operating free-air temperature range: SN54'	– 55 °C to 125 °C
SN74′	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

			SN5410 SN7410					
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	v
VIH	High-level input voltage	2			2			v
V _{IL}	Low-level input voltage			0.8			0.8	v
юн	High-level output current			- 0.4			- 0.4	mA
IOL	Low-level output current			16			16	mA
Τ _Α	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS T	SN5410	SN7410	
		MIN TYP‡ M	X MIN TYPE MAX	
VIK	$V_{CC} = MIN, I_{I} = -12 \text{ mA}$	-	.5 – 1.5	V
VOH	V_{CC} = MIN, V_{1L} = 0.8 V, I_{OH} = -0.4 m	A 2.4 3.4	2.4 3.4	V
VOL	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA	0.2 (0.4 0.2 0.4	V
1	V _{CC} = MAX, V _I = 5.5 V		1 1	mA
Чн	V _{CC} = MAX, V _I = 2.4 V		40 40	μA
11L	V _{CC} = MAX, V _I = 0.4 V	_ 1	.6 – 1.6	mA
IOS§	V _{CC} = MAX	- 20 -	55 – 18 – 55	mA
Іссн	V _{CC} = MAX, V ₁ = 0 V	3	6 3 6	mA
ICCL	V _{CC} = MAX, V ₁ = 4.5 V	9 16	.5 9 16.5	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM	то					
TANAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
^t PLH	A, B or C	· ·			11	22	ns
^t PHL		Ť	$R_{L} = 400 \Omega, \qquad C_{L} = 15 pF$		7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SN54LS10, SN74LS10, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

	SN54LS10			•	UNIT		
	 MIN	NOM	MAX	MIN	NOM	MAX	UNII
V _{CC} Supply voltage	 4.5	5	5.5	4.75	5	5.25	v
VIH High-level input voltage	2			2			v
VIL Low-level input voltage			0.7			0.8	v
IOH High-level output current			- 0.4		· · ·	- 0.4	mA
IOL Low-level output current			4			8	mA
T _A Operating free-air temperatu	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDI	rione t		SN54LS	10		SN74LS	510 ·	
FARAMETER		TEST CONDIT		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	l _l = – 18 mA				- 1.5			- 1.5	V
V _{OH}	V _{CC} = MIN,	VIL = MAX,	l _{OH} = 0.4 mA	2.5	3.4		2.7	3.4		V
N.c.	V _{CC} = MIN,	V _{IH} = 2 V,	1 _{OL} = 4 mA		0.25	0.4	[0.4	
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	IOL = 8 mA				1	0.25	0.5	-
Ι _Ι	V _{CC} = MAX,	V ₁ = 7 V		1		0.1			0.1	mA
ųн	V _{CC} = MAX,	V ₁ = 2.7 V				20	1		20	μΑ
ίιΓ	V _{CC} = MAX,	V1 = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX,	V _I = 0 V			0.6	1.2		0.6	1.2	mA
ICCL	V _{CC} = MAX,	V ₁ = 4.5 V			1.8	3.3		1.8	3.3	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN	түр	мах	UNIT	
tPLH	A, B or C	Y	$R_1 = 2 k \Omega_2$	C _I = 15 pF		9	15	ns
^t PHL	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		n [- 2 kst, C [- 15 pr			10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

			SN54S10 SN74S10			10	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	v
VIH	High-level input voltage	2			2			v
VIL	Low-level input voltage			0.8			0.8	v
юн	High-level output current			- 1			- 1	mA
IOL	Low-level output current			20	1		20	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN54S10	SN74S10	
PARAMETER	TEST CONDITIONS †	MIN TYP‡ MAX	MIN TYP‡ MAX	UNIT
ν _{ικ}	V _{CC} = MIN, I _I = -18 mA	-1.2	-1.2	v
V _{OH}	$V_{CC} \approx MIN$, $V_{IL} = 0.8 V$, $I_{OH} = -1 mA$	2,5 3,4	2.7 3.4	v
VOL	$V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 20 mA$	0.5	0.5	v
lj	V _{CC} = MAX, V _I = 5.5 V	1	1	mA
ін	V _{CC} = MAX, V _I = 2.7 V	50	50	μA
ŧι∟	V _{CC} = MAX, V _I = 0.5 V	-2	-2	mA
IOS §	V _{CC} = MAX	-40 -100	-40 -100	mA
^I ССН	V _{CC} = MAX, V _I = 0 V	7.5 12	7.5 12	mA
ICCL	V _{CC} = MAX, V _I = 4.5 V	15 27	15 27	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

то FROM PARAMETER **TEST CONDITIONS** MIN ТҮР MAX UNIT (INPUT) (OUTPUT) 3 4.5 **tPLH** ns $R_L = 280 \Omega$, C_L = 15 pF TPHL 3 5 ns A, B or C Y 4.5 ^tPLH ns $R_L = 280 \Omega$, CL = 50 pF 5 ^tPHL ns

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07005BCA	Samples
JM38510/07005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07005BDA	Samples
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30005B2A	Samples
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30005BCA	Samples
JM38510/30005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30005BDA	Samples
JM38510/30005SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30005SDA	Samples
M38510/07005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07005BCA	Samples
M38510/07005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07005BDA	Samples
M38510/30005B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30005B2A	Samples
M38510/30005BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30005BCA	Samples
M38510/30005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30005BDA	Samples
M38510/30005SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30005SDA	Samples
SN54LS10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS10J	Samples
SN54S10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S10J	Samples
SN74LS10D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples
SN74LS10DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples
SN74LS10DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples



24-Aug-2018

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LS10DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS10	Samples
SN74LS10N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS10N	Samples
SN74LS10NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS10	Samples
SN74S10N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S10N	Samples
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 10FK	Samples
SNJ54LS10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS10J	Samples
SNJ54LS10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS10W	Samples
SNJ54S10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S10J	Samples
SNJ54S10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S10W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

ROHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS10, SN54LS10-SP, SN54S10, SN74LS10, SN74S10 :

- Catalog: SN74LS10, SN54LS10, SN74S10
- Military: SN54LS10, SN54S10
- Space: SN54LS10-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS

Texas Instruments





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS10DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS10NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS10DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS10NSR	SO	NS	14	2000	367.0	367.0	38.0

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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